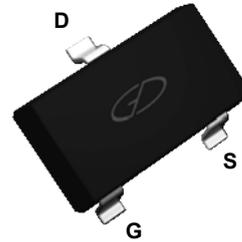
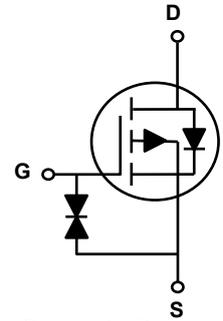


## Main Product Characteristics

$BV_{DSS}$	-25V
$R_{DS(ON)}$	640m $\Omega$
$I_D$	-0.85A



SOT-23



Schematic Diagram

## Features and Benefits

- Advanced MOSFET process technology
- Ideal for high efficiency switched mode power supplies
- Low on-resistance with low gate charge
- Fast switching and reverse body recovery



## Description

The GSFC02501 utilizes the latest techniques to achieve high cell density and low on-resistance. These features make this device extremely efficient and reliable for use in high efficiency switch mode power supplies and a wide variety of other applications.

## Absolute Maximum Ratings ( $T_J=25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	Max.	Unit
Drain-Source Voltage	$V_{DS}$	-25	V
Gate-Source Voltage	$V_{GS}$	$\pm 8$	V
Drain Current-Continuous ( $T_A=25^\circ\text{C}$ ) <sup>1,3</sup>	$I_D$	-0.85	A
Drain Current-Continuous ( $T_A=70^\circ\text{C}$ ) <sup>1,3</sup>		-0.68	
Drain Current-Pulsed <sup>2</sup>	$I_{DM}$	-2.1	A
Power Dissipation ( $T_A=25^\circ\text{C}$ )	$P_D$	0.69	W
Power Dissipation ( $T_A=70^\circ\text{C}$ )		0.44	
Thermal Resistance, Junction-to-Ambient <sup>1</sup>	$R_{\theta JA}$	180	$^\circ\text{C/W}$
Operating Junction Temperature Range	$T_J$	-55 To +150	$^\circ\text{C}$
Storage Temperature Range	$T_{STG}$	-55 To +150	$^\circ\text{C}$

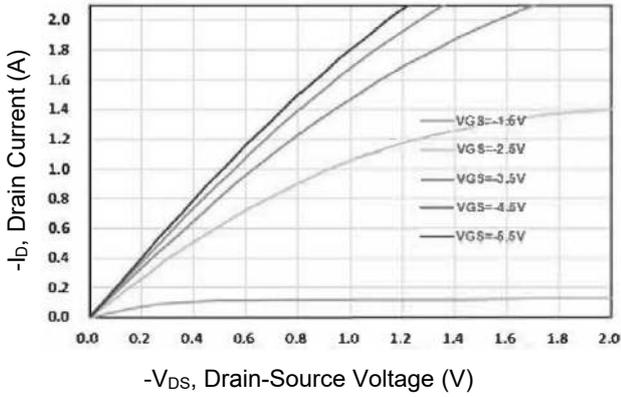
**Electrical Characteristics** ( $T_J=25^\circ\text{C}$  unless otherwise specified)

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
<b>On / Off Characteristics</b>						
Drain-Source Breakdown Voltage	$BV_{DSS}$	$V_{GS}=0V, I_D=-250\mu A$	-25	-	-	V
Drain-Source Leakage Current	$I_{DSS}$	$V_{DS}=-16V, V_{GS}=0V$	-	-	-1	$\mu A$
Gate-Source Leakage Current	$I_{GSS}$	$V_{GS}=\pm 12V, V_{DS}=0V$	-	-	$\pm 10$	$\mu A$
Static Drain-Source On-Resistance	$R_{DS(ON)}$	$V_{GS}=-4.5V, I_D=-0.55A$	-	530	640	m $\Omega$
		$V_{GS}=-2.5V, I_D=-0.45A$	-	730	950	
		$V_{GS}=-1.8V, I_D=-0.35A$	-	1300	1950	
Gate Threshold Voltage	$V_{GS(th)}$	$V_{GS}=V_{DS}, I_D=-250\mu A$	-0.5	-	-1	V
Forward Transconductance	$g_{fs}$	$V_{DS}=-5V, I_D=-0.55A$	-	1	-	S
<b>Dynamic and Switching Characteristics</b>						
Total Gate Charge <sup>3,4</sup>	$Q_g$	$V_{GS}=-2.5V, V_{DS}=-10V, I_D=-1A$	-	0.53	-	nC
Total Gate Charge <sup>3,4</sup>	$Q_g$	$V_{DS}=-10V, I_D=-1A, V_{GS}=-4.5V$	-	0.8	-	nC
Gate-Source Charge <sup>3,4</sup>	$Q_{gs}$		-	0.2	-	
Gate-Drain Charge <sup>3,4</sup>	$Q_{gd}$		-	0.2	-	
Turn-On Delay Time <sup>3,4</sup>	$t_{d(on)}$	$V_{DS}=-10V, R_G=3\Omega, V_{GS}=-4.5V, I_D=-1.33A$	-	400	-	nS
Rise Time <sup>3,4</sup>	$t_r$		-	60	-	
Turn-Off Delay Time <sup>3,4</sup>	$t_{d(off)}$		-	20	-	
Fall Time <sup>3,4</sup>	$t_f$		-	800	-	
Input Capacitance	$C_{iss}$	$V_{DS}=-10V, V_{GS}=0V, F=1MHz$	-	58	-	pF
Output Capacitance	$C_{oss}$		-	5.7	-	
Reverse Transfer Capacitance	$C_{rss}$		-	4.4	-	
<b>Drain-Source Diode Characteristics and Maximum Ratings</b>						
Diode Forward Voltage	$V_{SD}$	$V_{GS}=0V, I_{SD}=-1A$	-	-	-1.1	V
Reverse Recovery Time	$t_{rr}$	$I_F=-1A,$	-	9.2	-	nS
Reverse Recovery Charge	$Q_{rr}$	$di/dt=100A/\mu s$	-	0.8	-	nC

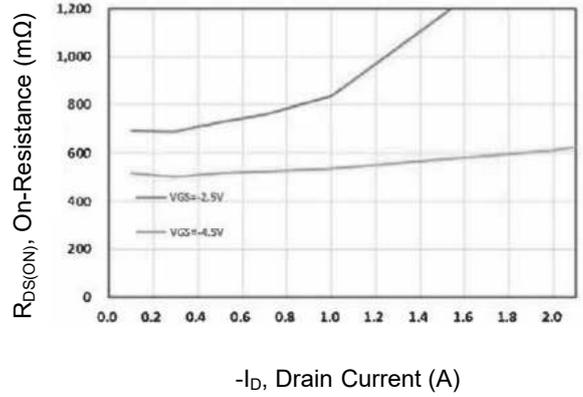
Notes:

1. The value of  $R_{\theta JA}$  is measured with the device mounted on 1in<sup>2</sup> FR-4 board with 2oz. Copper, in a still air environment with  $T_A=25^\circ\text{C}$ . The value in any given application depends on the user's specific board design.
2. Repetitive rating, pulse width limited by junction temperature.
3. The current rating is based on the  $t < 10s$  junction to ambient thermal resistance rating.

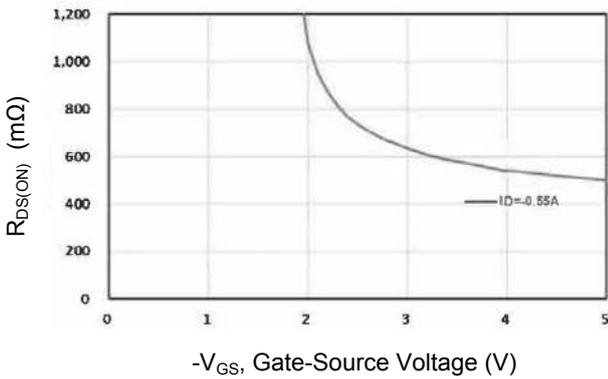
**Typical Electrical and Thermal Characteristic Curves**



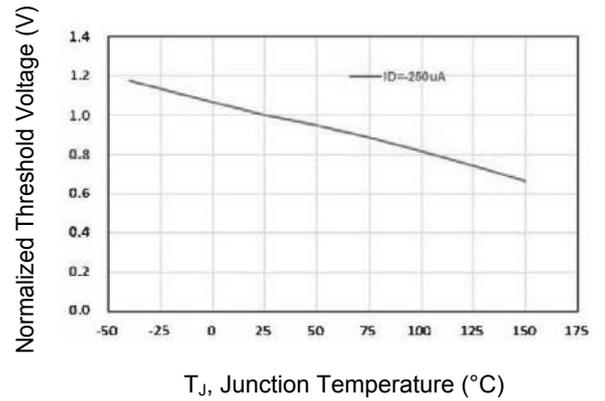
**Figure 1. Output Characteristics**



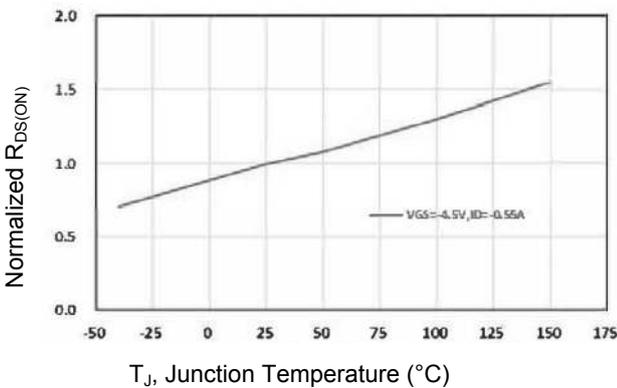
**Figure 2. On-Resistance vs.  $I_D$**



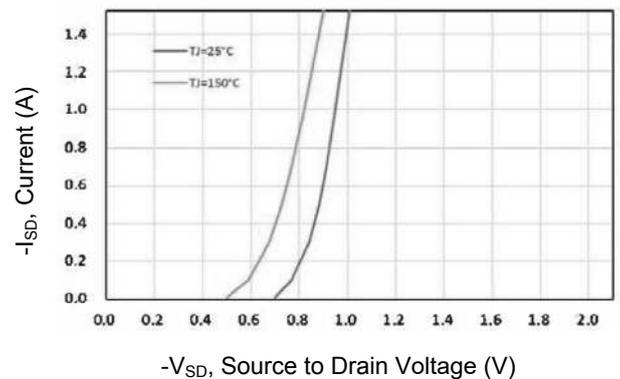
**Figure 3. Power Dissipation**



**Figure 4. Gate Threshold Voltage**

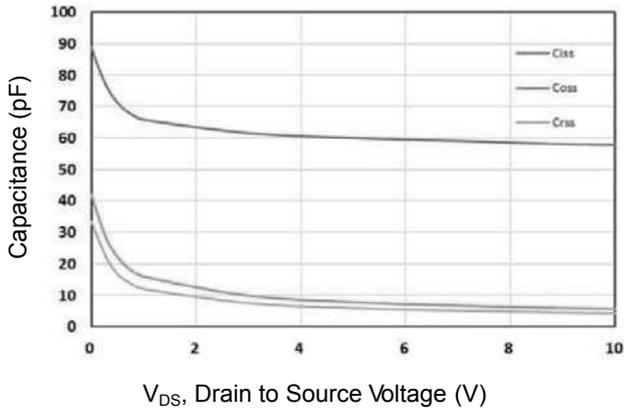


**Figure 5. Drain-Source On Resistance**

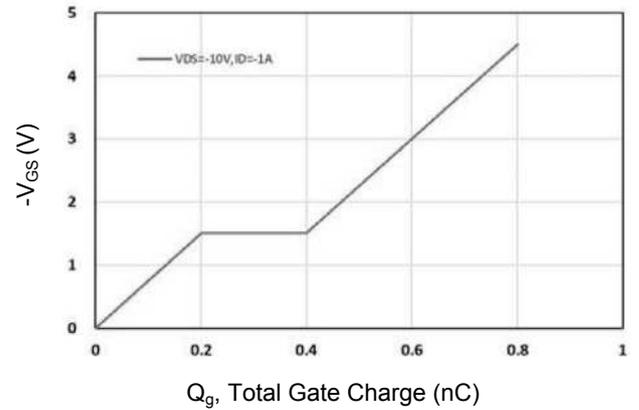


**Figure 6. Source-Drain Diode Forward**

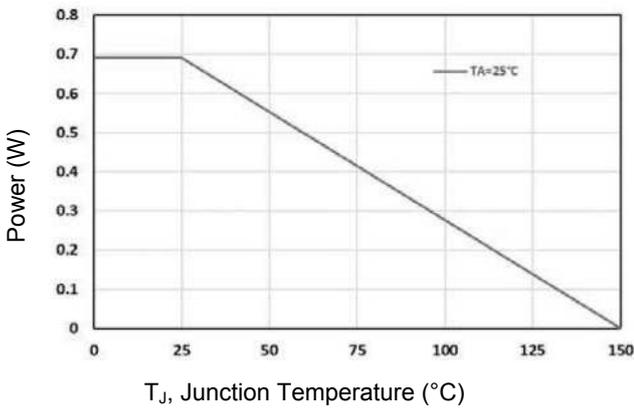
**Typical Electrical and Thermal Characteristic Curves**



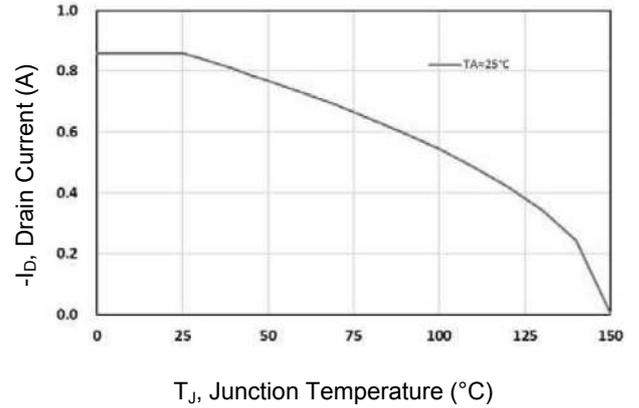
**Figure 7. Capacitance Characteristics**



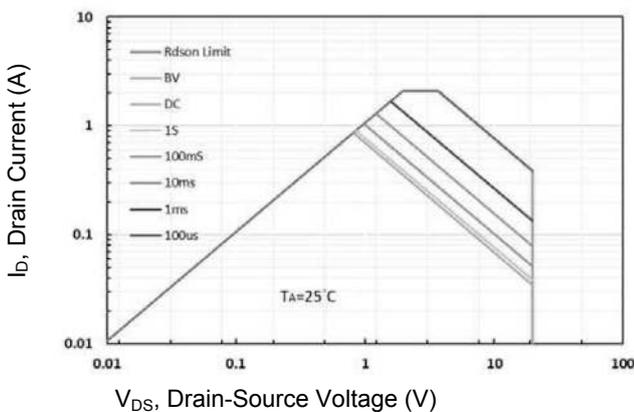
**Figure 8. Gate Charge Characteristics**



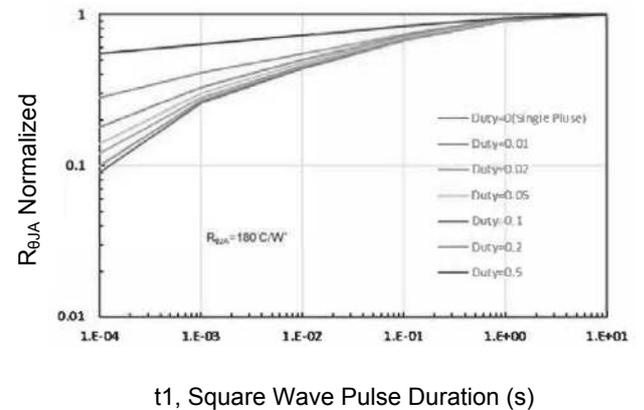
**Figure 9. Power Dissipation**



**Figure 10. Drain Current**

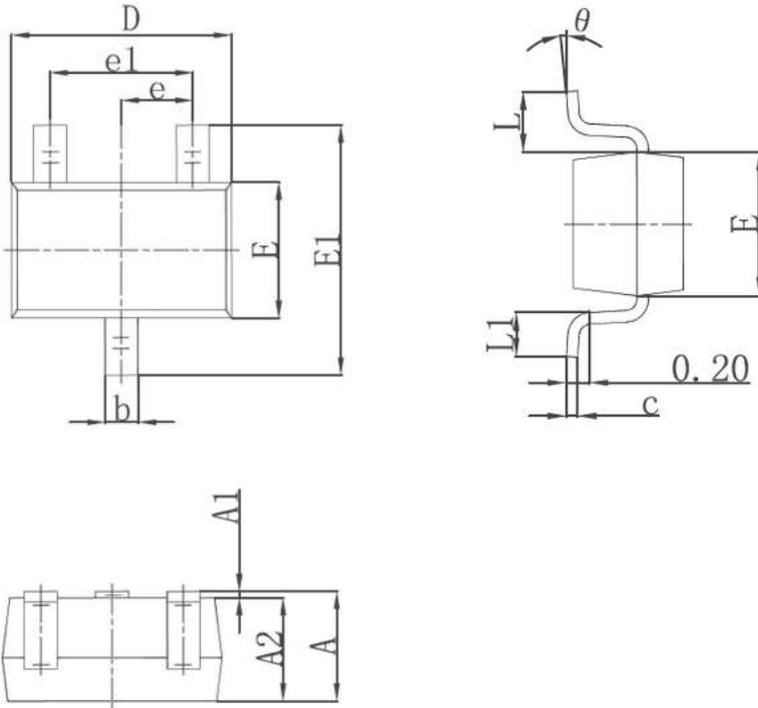


**Figure 11. Safe Operating Area**



**Figure 12. R<sub>θJA</sub> Transient Thermal Impedance**

**Package Outline Dimensions (SOT-23)**



Symbol	Dimensions in Millimeters		Dimensions in Inches	
	Min	Max	Min	Max
A	0.900	1.100	0.035	0.043
A1	0.000	0.100	0.000	0.004
A2	0.900	1.000	0.035	0.039
b	0.200	0.400	0.008	0.016
c	0.080	0.150	0.003	0.006
D	2.000	2.200	0.079	0.087
E	1.150	1.350	0.045	0.053
E1	2.150	2.450	0.085	0.096
e	0.650 TYP		0.026 TYP	
e1	1.200	1.400	0.047	0.055
L	0.525 REF		0.021 REF	
L1	0.260	0.460	0.010	0.018
theta	0°	8°	0°	8°